

Trapping in p-on-n silicon sensors at fluences relevant for the HL-LHC

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Institute of Experimental Physics

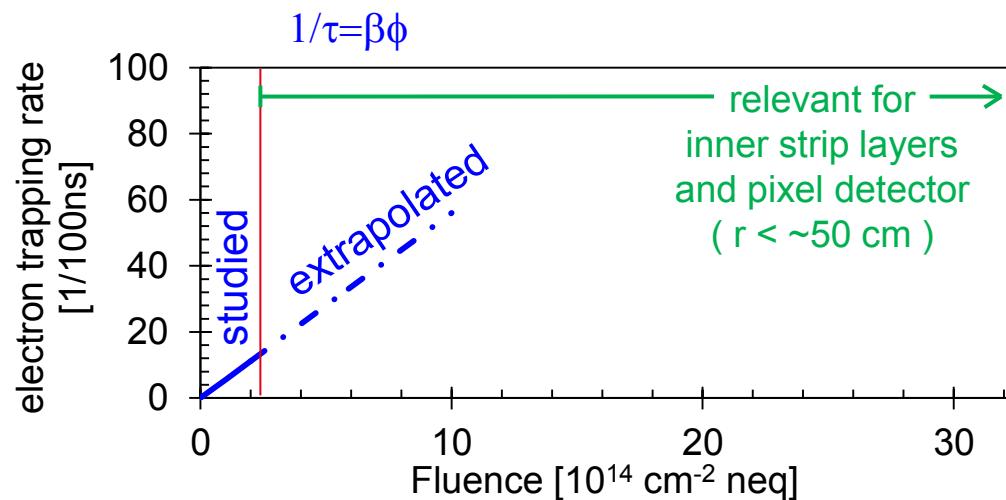
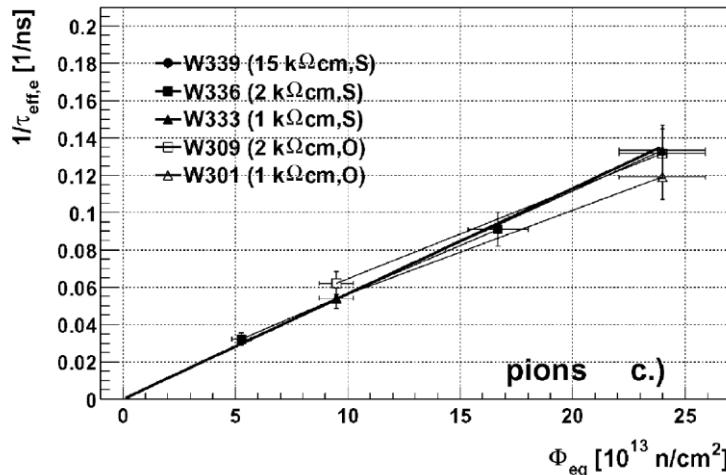
University of Hamburg

Motivation

- A correct description of charge losses in the Si bulk is essential in order to simulate the detector performance at the HL-LHC, especially in the inner detector layers.
- So far trapping in CMS tools is based on effective trapping rates according to G. Kramberger:

$$\frac{1}{\tau_{e,h}} = \sum_i \frac{1}{\tau_{e,h}^i} = \sum_i N_{e,h}^i \cdot \sigma_{e,h}^i \cdot v_{e,h} = \beta_{e,h} \cdot \phi$$

G. Kramberger et al., NIM A 481 (2002) 297–305

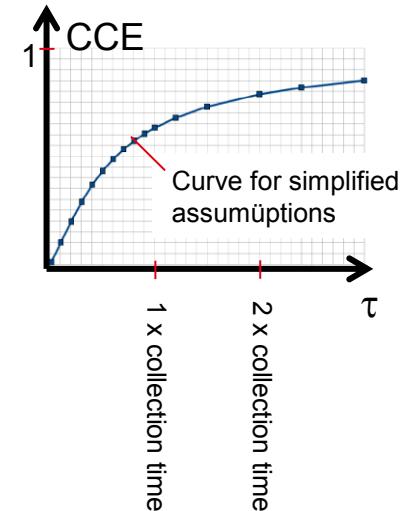


Method to determine the trapping rates

1. Use red laser TCT measurements (672 nm)
 \Rightarrow Study electron and hole drift separately



2. Simulate red laser TCT measurements assuming
 - **Electric field** based on **2 effective defects*** (Donor: $E_V + 0.48$ eV, Acceptor: $E_C - 0.525$ eV)
 Different E-field distributions are tested
 - **Drift velocity** independent of irradiation dose
 - Effective **trapping rate** independent of position (-> only two free parameters: τ_e, τ_h)
3. Fit the CCE at a given voltage ($V = 600$ V) using 1 free fit parameter:
 τ_e (for front illumination) or τ_h (for rear illum.)
4. Perform cross-checks:
 - a) Compare measured and simulated TCT signals $I(t)$
 - b) Predict the CCE for measurements using infrared laser light

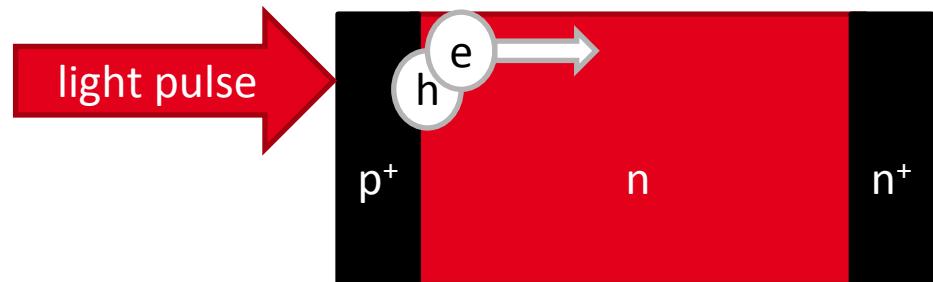


*EVL model: NIM A 476 (2002) 556-564.

Transient current technique (TCT)

red laser light pulse:

- 672 nm, 3.5 μm penetration depth
- FWHM 40 ps
- generates $N = \sim 1$ million e-h pairs

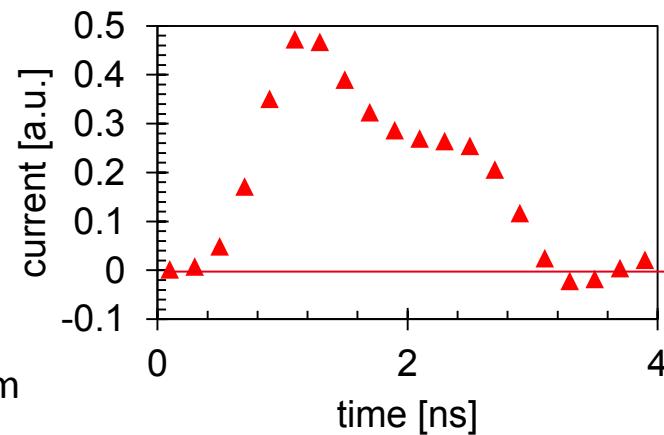


$$\Rightarrow \text{induced current (pad sensor)} : I = \sum_{\text{free carriers } i} \frac{q_i}{d} \cdot \frac{\Delta x_i}{\Delta t}, \quad \frac{\Delta x_i}{\Delta t} \approx v_{dr} = \mu(E) \cdot E$$

$$Q = \int I dt, \quad CCE = \frac{Q_{\text{irradiated}}}{Q_{\text{non-irradiated}}} = \frac{Q}{Q_0}$$

readout:

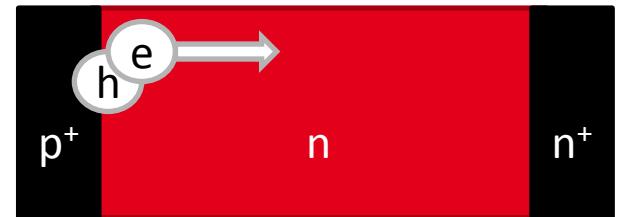
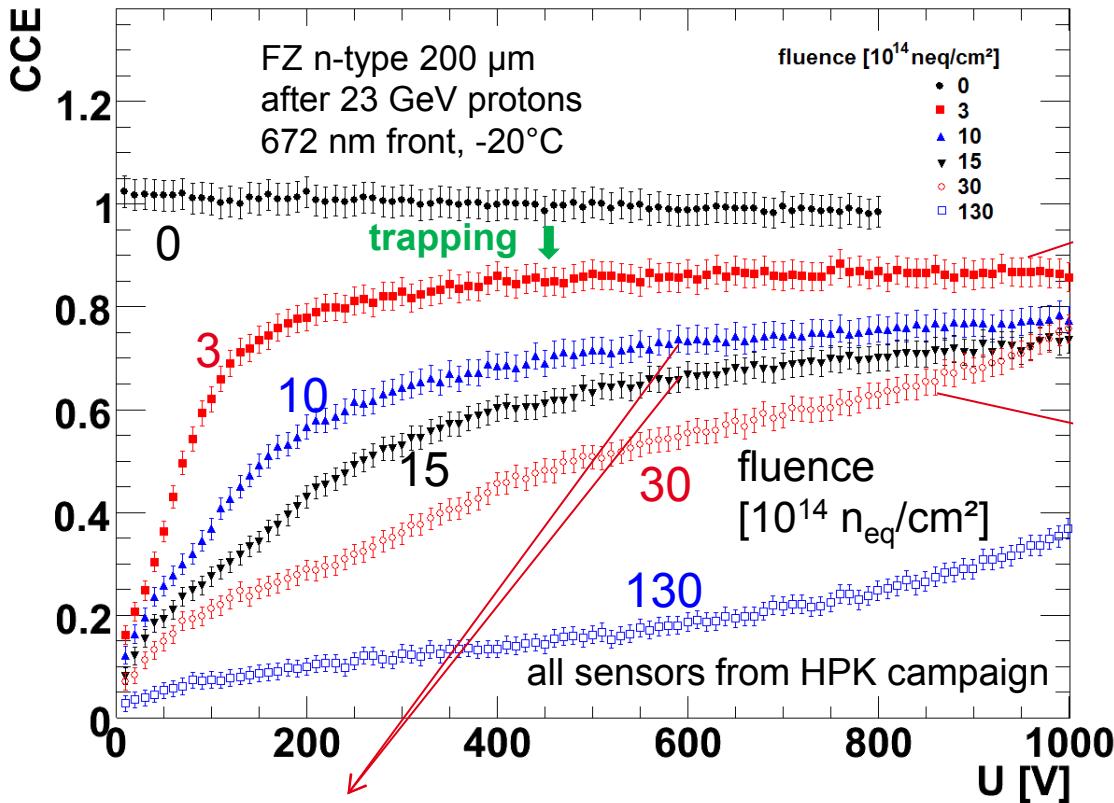
- digital oscilloscope (bandwidth 1 GHz, 512 averages)
- 10 x Phillips current amplifier
- diode capacitance of ~ 2 pF for the used diodes with $d=200 \mu\text{m}$



Transient current technique (TCT)

→ CCE for different fluences (23 GeV protons)

$$CCE = \frac{Q_{\text{irradiated}}}{Q_{\text{non-irradiated}}^{400V}} = \frac{Q}{Q_0}$$



CCE uncertainty: 3%
 (2% syst. due to voltage dependence,
 2% reproducibility)

Here protons only (not mixed):
 ⇒ comparable with earlier studies

Study in detail: 10 and $15 \cdot 10^{14} \text{ neq}/\text{cm}^2$ at 600 V (simulate $I(t)$ in PixelAV)

CCE => trapping rate (for electrons), assuming $E(x)$, $v_{\text{dr}}(E)$

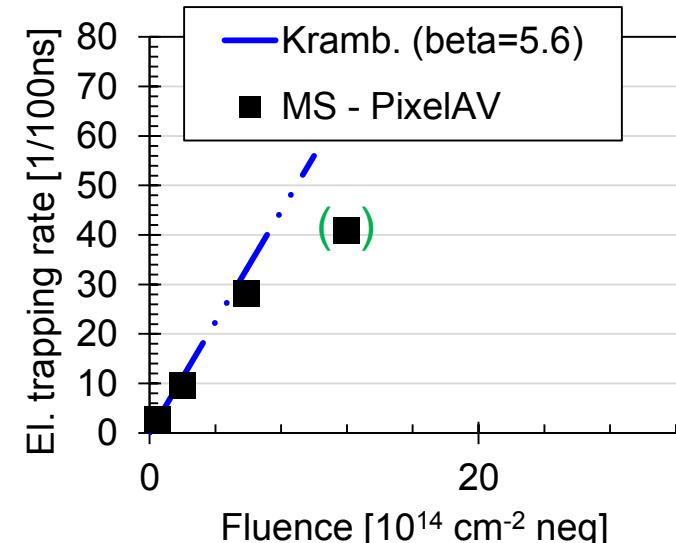
E(x) – Tuning of two effective defects

Fit by Morris Swartz et al. using TCAD and self-written „PixelAV“ simulation program and grazing angle measurements ([arXiv:physics/0605215](https://arxiv.org/abs/physics/0605215)):

For 285 μm thick pixel sensors (125 μm x 125 μm , DO-FZ, n-in-n, p-spray)

Tuned: N_D , N_A , σ_e^D , σ_h^D , σ_e^A , σ_h^A

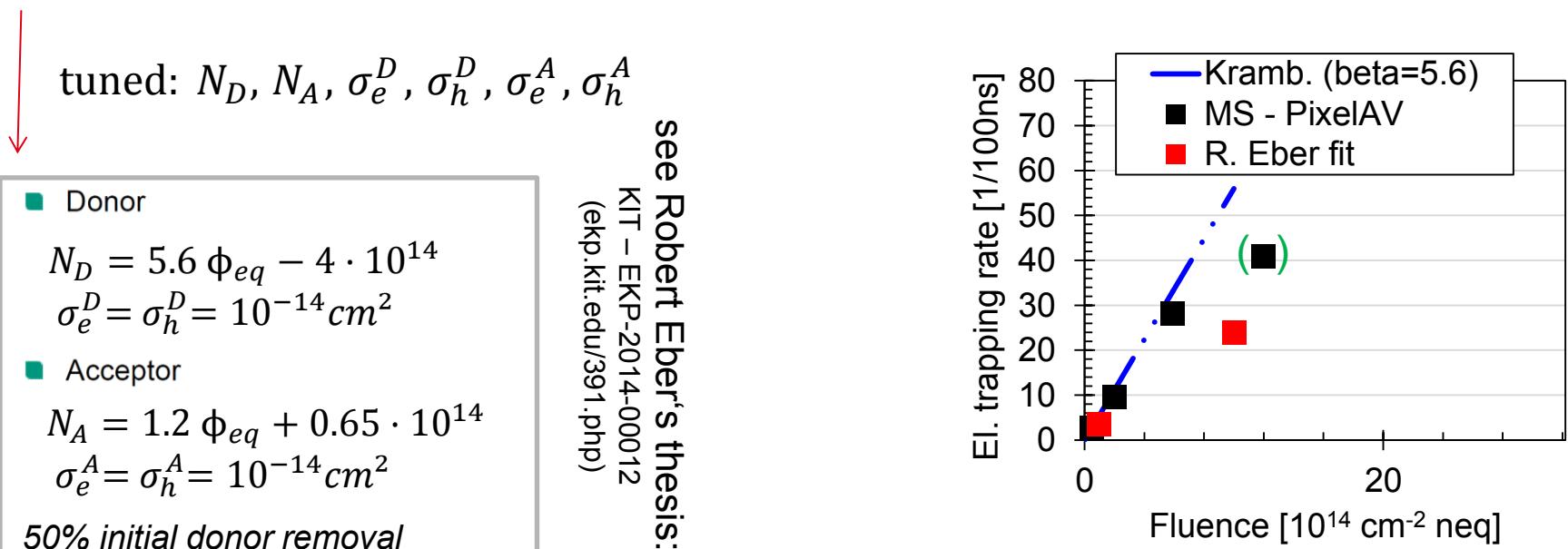
	arXiv:physics/0605215	Private communic. M. Swartz	
Φ [$10^{14} \text{ n}_{\text{eq}} \text{ cm}^{-2}$]	0.5 2.0 5.9	12	
N_A [10^{14} cm^{-3}]	1.9 6.8 16	30.	
N_D [10^{14} cm^{-3}]	2.5 10 40	69.	
σ_e^A/D [10^{-15} cm^2]	6.60 6.60 6.60	3.8/0.94	defects to describe E-field
σ_h^A [10^{-15} cm^2]	1.65 1.65 1.65	3.8	
σ_h^D [10^{-15} cm^2]	6.60 6.60 1.65	0.94	
Γ_e [10^{-2} ns^{-2}]	2.7 9.6 28.	41	trapping rates used in PixelAV
Γ_h [10^{-2} ns^{-2}]	3.6 13. 38.	55.	



E(x) – Tuning of two effective defects

Fit in TCAD by Robert Eber (KIT) using **current**, **capacitance** and **red laser TCT** meas.
after **23 MeV proton irradiation**, 300 µm thick, dd-FZ p-on-n pad sensors

IV, CV & TCT

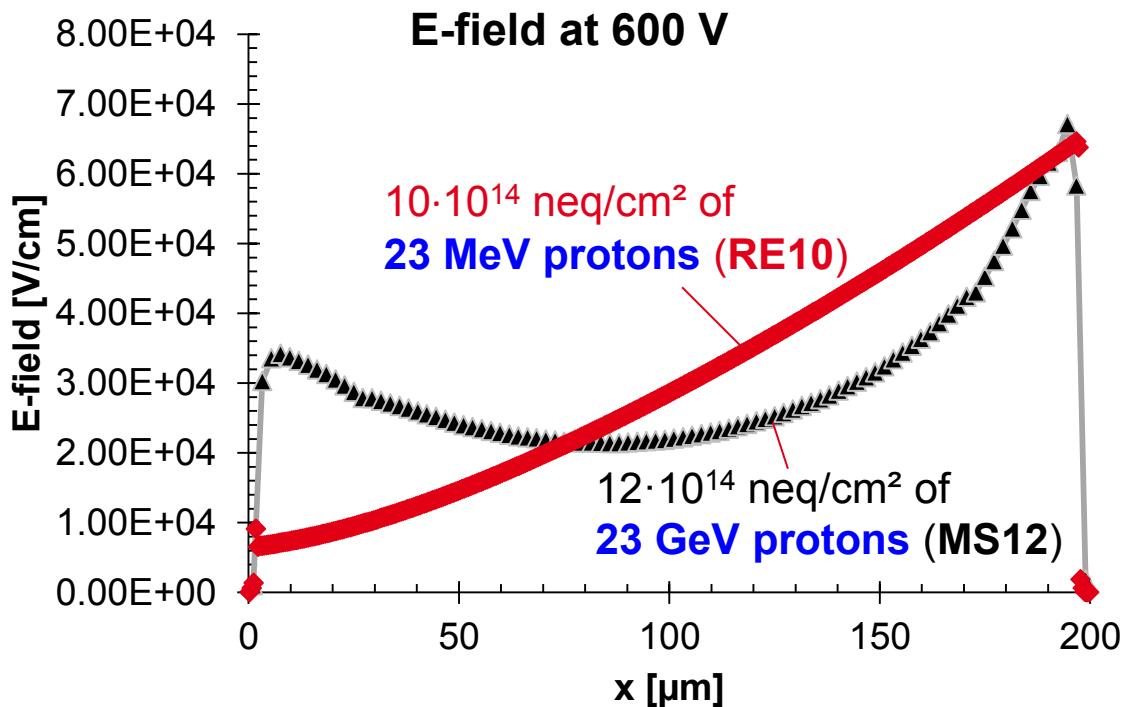


Next step: Determine the effective trapping rates directly from measured charge losses

E(x) – Simulation of TCT measurements

Studies by **Morris Swartz (MS12)** and by **Robert Eber (RE10)**

both: tune two eff. defects -> different E-fields! ... **different proton energies used**



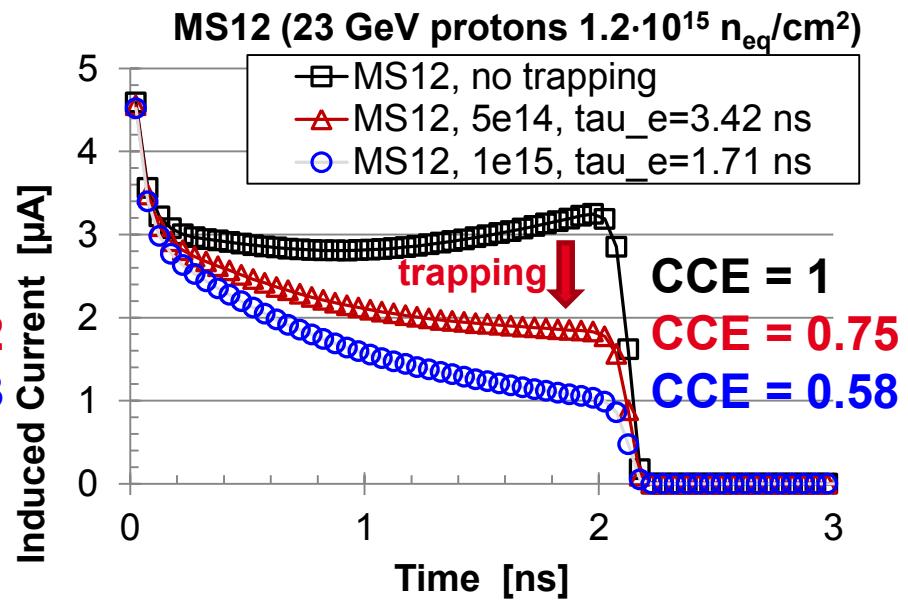
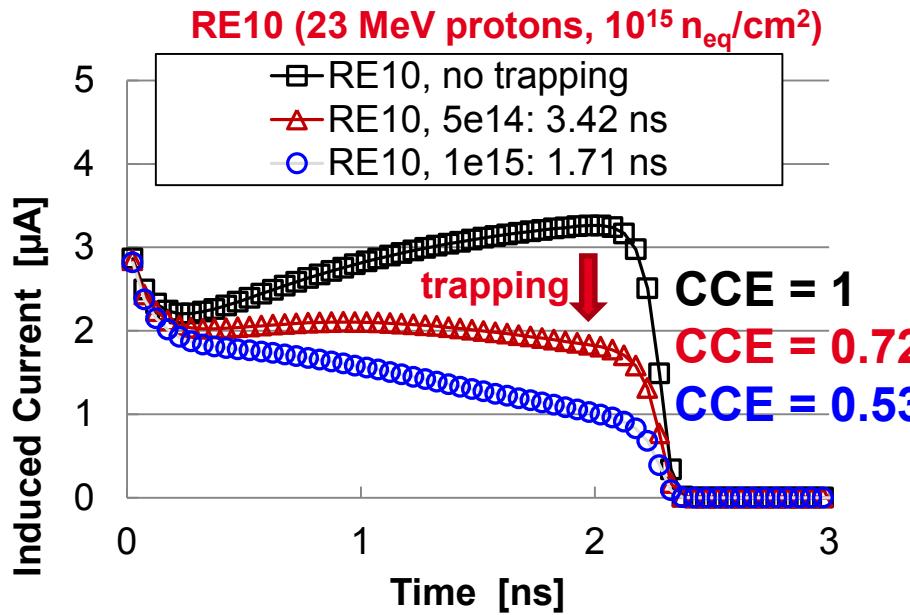
Modified PixelAV:

- time-resolved signals
- linear weighting potential
- drift velocity for <100> Si (independent of dose)
- 40 000 eh pairs are generated at the front (3.5 μm penetration):



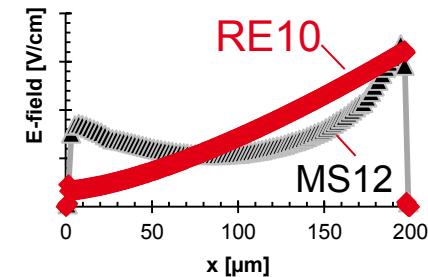
- vary the trapping time τ_e (τ_h) to describe the CCE (assume $\tau_{e,h}$ independent of position)
- determine τ_e for both E-fields

Time-resolved current signals

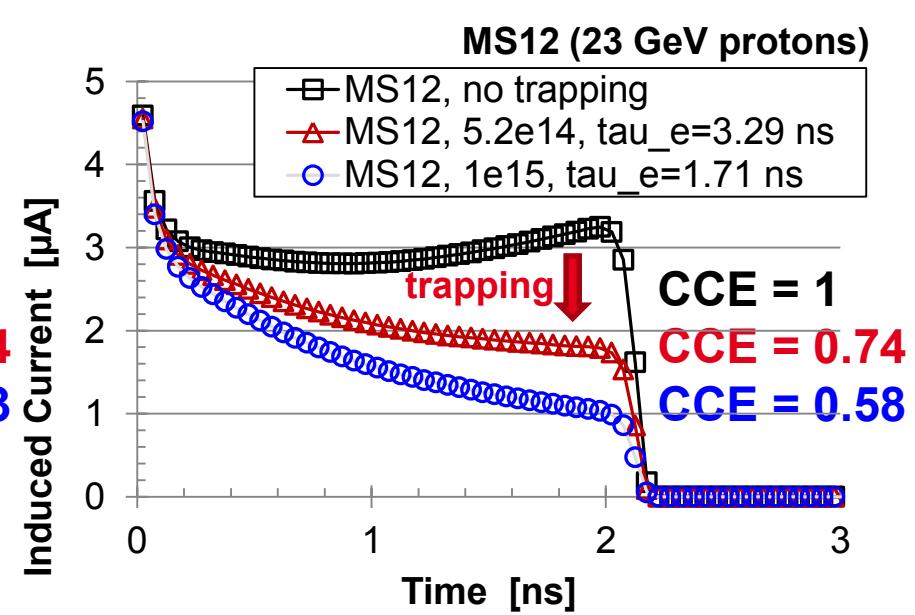
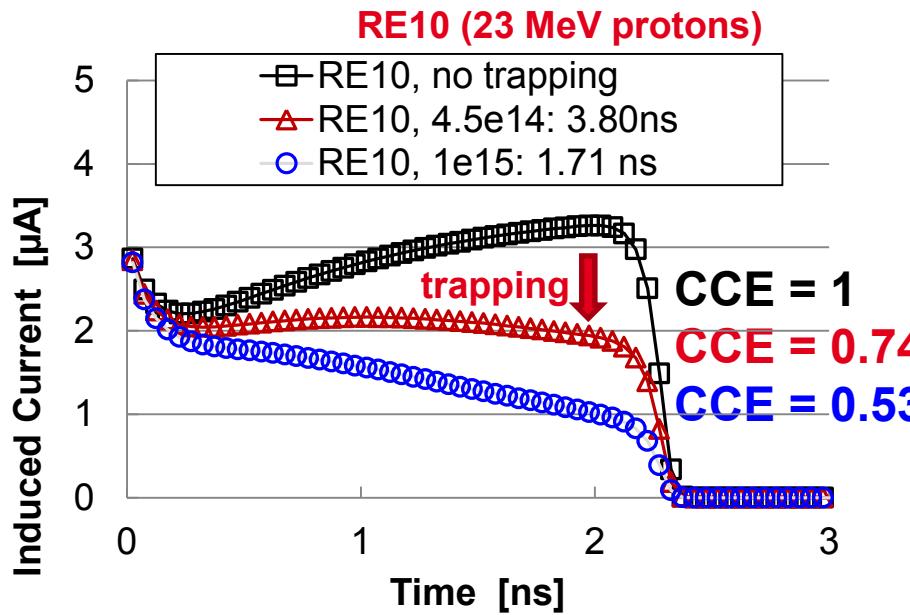


CCE measured = 0.74 (after 23 GeV proton irradiation to $1e15$)

⇒ adjust trapping time



Time-resolved current signals

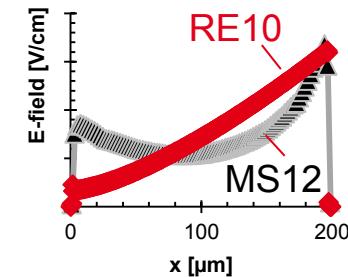


CCE measured = 0.74 (after 23 GeV proton irradiation to 1×10^{15})

for $10 \cdot 10^{14}$ neq/cm² :

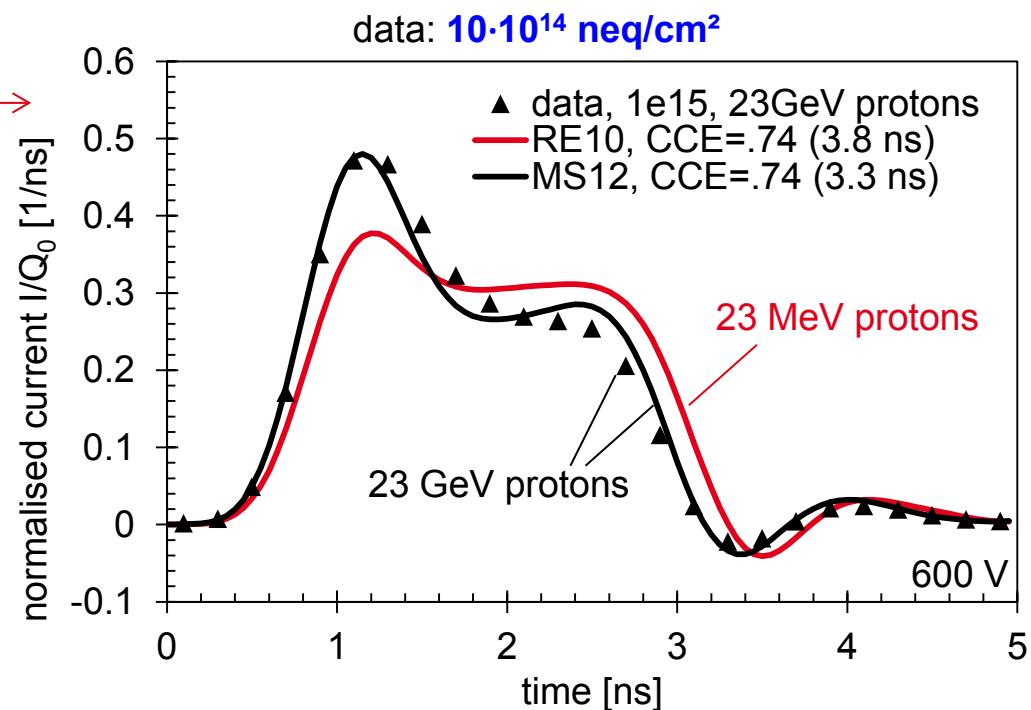
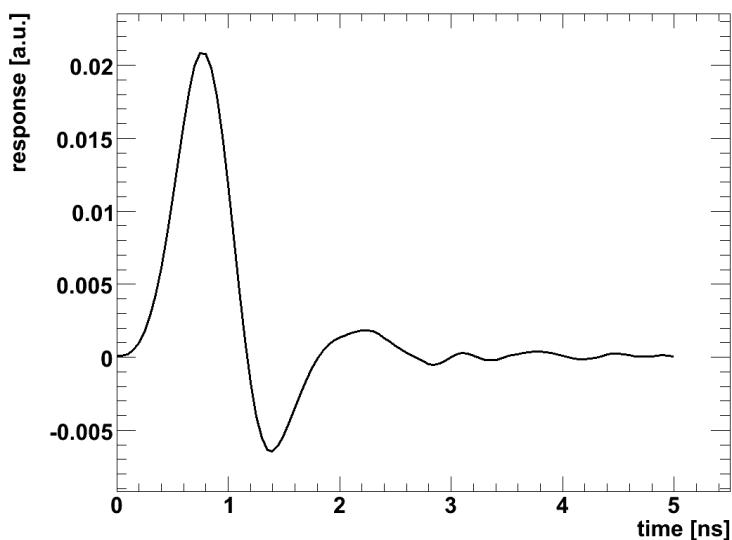
⇒ $\tau = 3.3 \text{ ns} \pm 0.4 \text{ ns}_{\text{CCE}}$ if we assume the field **MS12 (23 GeV protons)**

⇒ $\tau = 3.8 \text{ ns} \pm 0.4 \text{ ns}_{\text{CCE}}$ if we assume the field **RE10 (23 MeV protons)**



Time-resolved current signals – simulated and measured

Convolute simulated signal
 with **response of our TCT setup**
 to a delta function



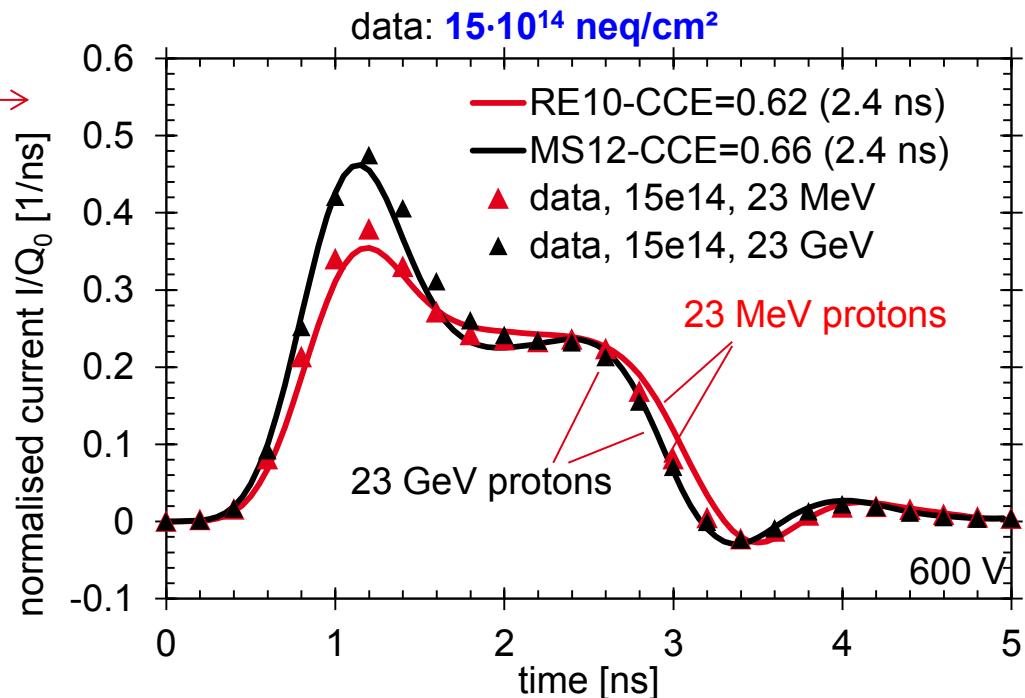
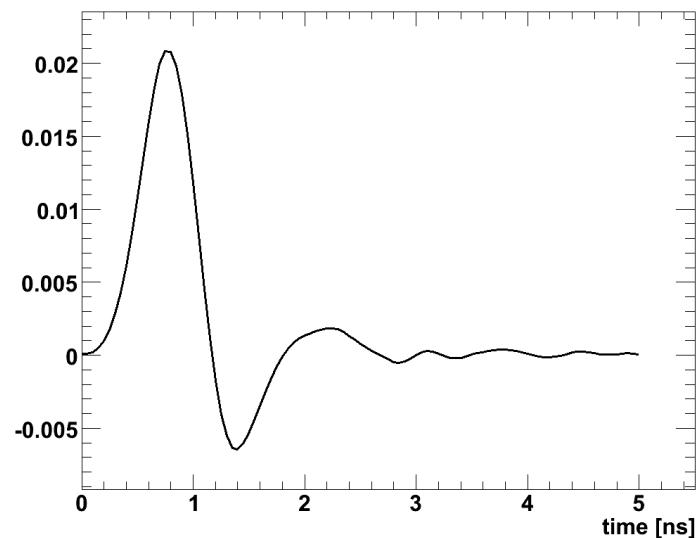
Measured TCT signal very compatible with the E-field according to M. Swartz (**MS12**)

for $10 \cdot 10^{14} \text{ neq/cm}^2$:

- ⇒ $\tau = 3.3 \text{ ns} \pm 0.4 \text{ ns}$ $_{\text{CCE}}$ if we assume the field **MS12 (23 GeV protons)** ✓
- ⇒ $\tau = 3.8 \text{ ns} \pm 0.4 \text{ ns}$ $_{\text{CCE}}$ if we assume the field **RE10 (23 MeV protons)**

Time-resolved current signals – simulated and measured

Convolute simulated signal
 with response of our TCT setup
 to a delta function



Measured TCT signal very compatible with the correct E-fields used

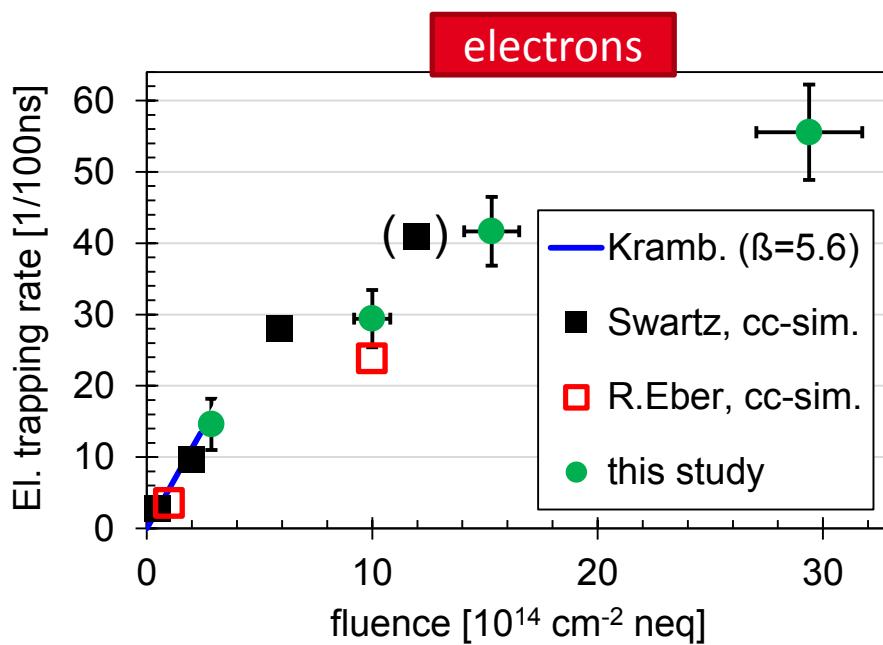
for $15 \cdot 10^{14}$ neq/cm² :

- ⇒ $\tau = 2.4 \text{ ns} \pm 0.3 \text{ ns}_{\text{CCE}}$ ✓ (for **23 GeV protons**, using **E-field MS12**)
- ⇒ $\tau = 2.4 \text{ ns} \pm 0.3 \text{ ns}_{\text{CCE}}$ ✓ (for **23 MeV protons**, using **E-field MS10**)

Results on the trapping rate

After 23 GeV protons:

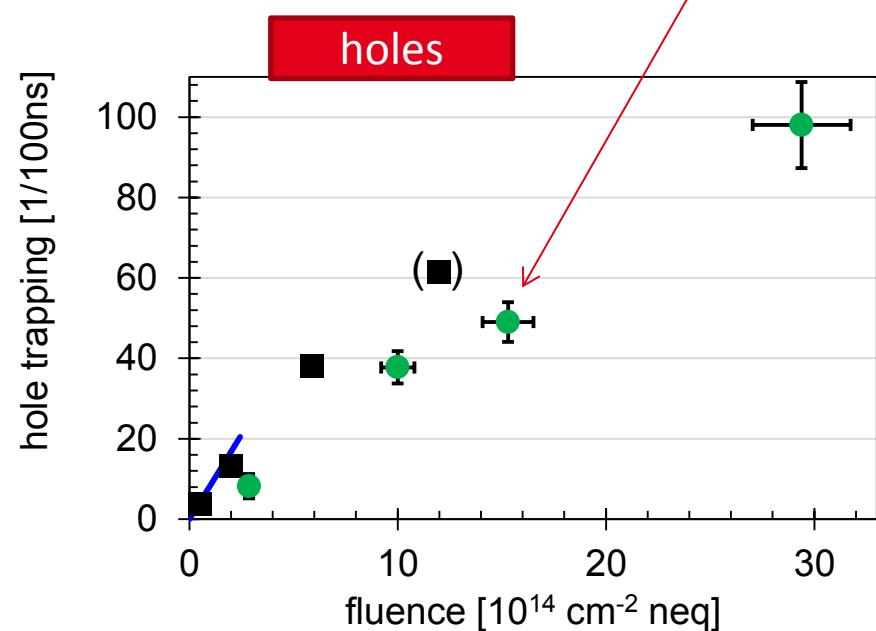
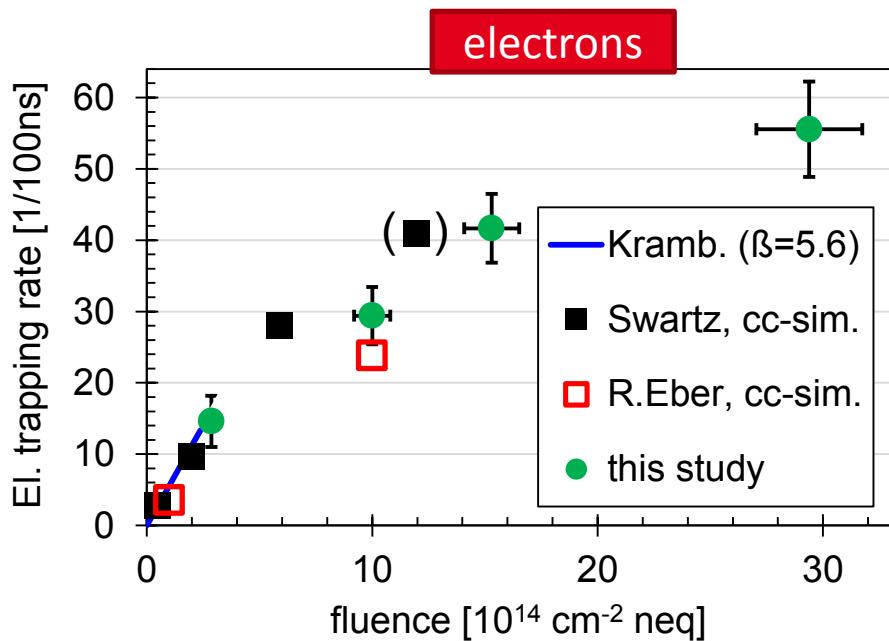
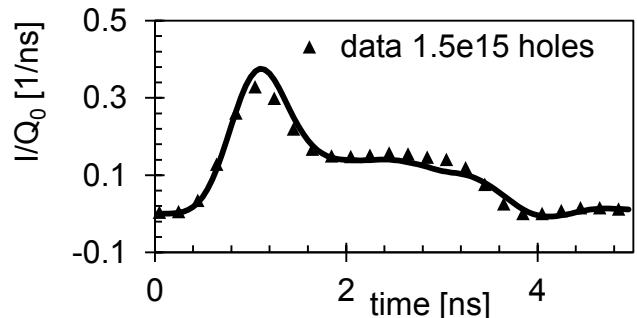
ϕ_{neq} [neq/cm ²]	$1/\tau_e$ [1/100 ns]
$3 \cdot 10^{14}$	$14.5 \pm 3.5_{\text{(CCE)}} \pm 0.5_{\text{(E-field)}}$
$1 \cdot 10^{15}$	$30 \pm 4_{\text{(CCE)}} \pm 3_{\text{(E-field)}}$
$1.5 \cdot 10^{15}$	$42 \pm 4_{\text{(CCE)}} \pm 3_{\text{(E-field)}}$
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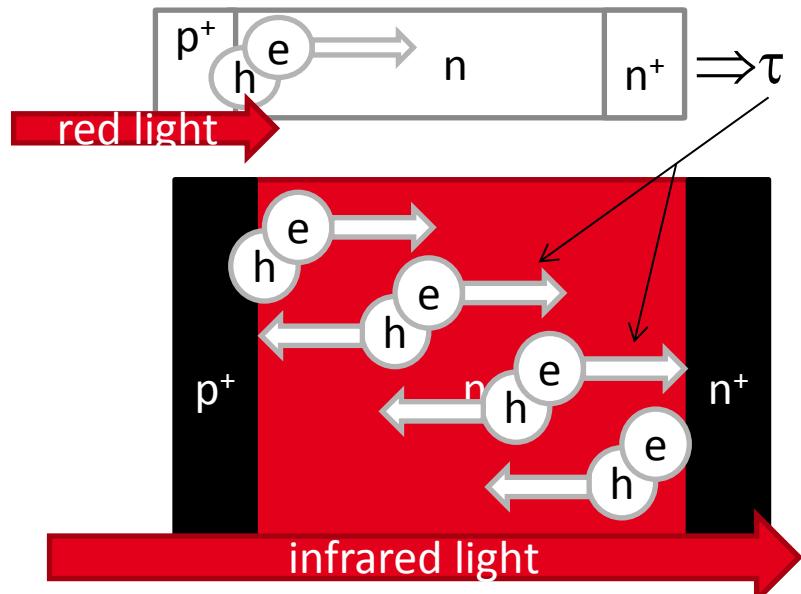
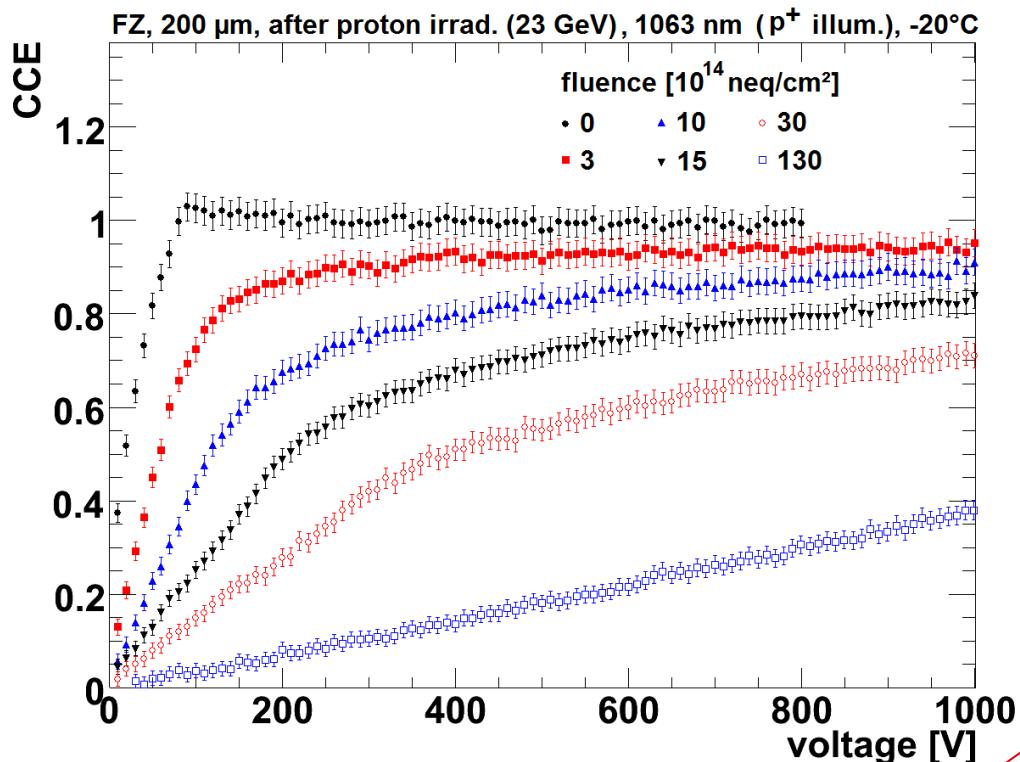
Results on the trapping rate

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ϕ_{neq} [neq/cm ²]	$1/\tau_e$ [1/100 ns]	$1/\tau_h$ [1/100 ns]
$3 \cdot 10^{14}$	14.5 ± 3.5 _(CCE) ± 0.5 _(E-field)	8.5 ± 2.5 _(CCE) ± 0.5 _(E-field)
$1 \cdot 10^{15}$	30 ± 4 _(CCE) ± 3 _(E-field)	38 ± 4 _(CCE) ± 4 _(E-field)
$1.5 \cdot 10^{15}$	42 ± 4 _(CCE) ± 3 _(E-field)	49 ± 5 _(CCE) ± 3 _(E-field)
$3 \cdot 10^{15}$	55 ± 6 _(CCE) ± 6 _(E-field)	98 ± 10 _(CCE) ± 12 _(E-field)



Check on infrared TCT measurements



At 600 V:

ϕ_{neq} [neq/cm 2]	CCE simulated A	CCE measured	CCE simulated B
$3 \cdot 10^{14}$	0.92 ± 0.03	0.93 ± 0.03	0.85 ± 0.02
$1 \cdot 10^{15}$	0.76 ± 0.03	0.85 ± 0.03	0.60 ± 0.03
$1.5 \cdot 10^{15}$	0.70 ± 0.03	0.75 ± 0.03	0.50 ± 0.03
$3 \cdot 10^{15}$	0.51 ± 0.03	0.60 ± 0.03	0.27 ± 0.02

this study

Kramberger extrapolated

Summary

Electron and hole drift (front- and rear-side illumination) **described using simulations**.

- **E(x) depends on the proton energy** used for irradiation (**23 GeV \neq 23 MeV**)

Effective trapping rates have been determined for fluences **relevant at the HL-LHC**,
(up to $\sim 3 \cdot 10^{15}$ neq/cm²) assuming uniform trapping rates.

At 600 V the results have little dependence on the E(x) assumptions.

For charge carriers generated along the sensor depth using IR light:

⇒ **CCE predictions** low, but **improved by a factor of ~3** compared to extrapolations

Comment: Higher CCE than expected also seen in 150 µm thick Epi sensors.

After neutron irrad: see my talk, 20th RD50, after proton irrad: see DESY-THESIS-2009-022 (Jörn Lange)

Outlook:

Shall there be another study on trapping at high fluences?

Studies might be extended to

- MCz and p-type Silicon (**so far FZ silicon with n-bulk only**)
- mixed irradiation (protons + neutrons) (**so far protons only**)
- Use position-dependent trapping rates ? => additional free parameters !

Summary

Electron and hole drift (front- and rear-side illumination) **described using simulations**.

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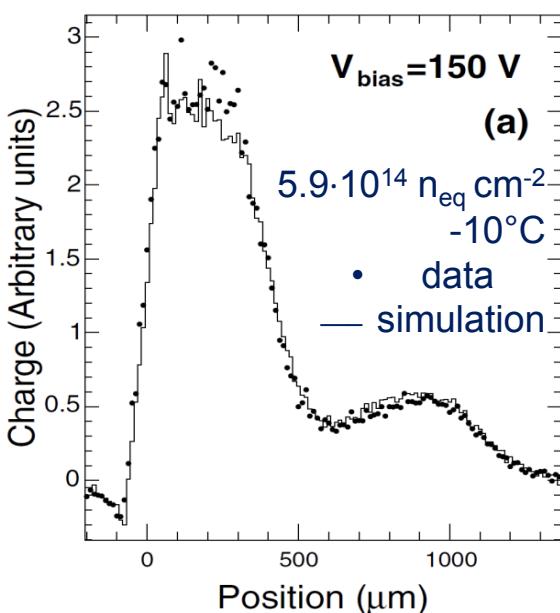
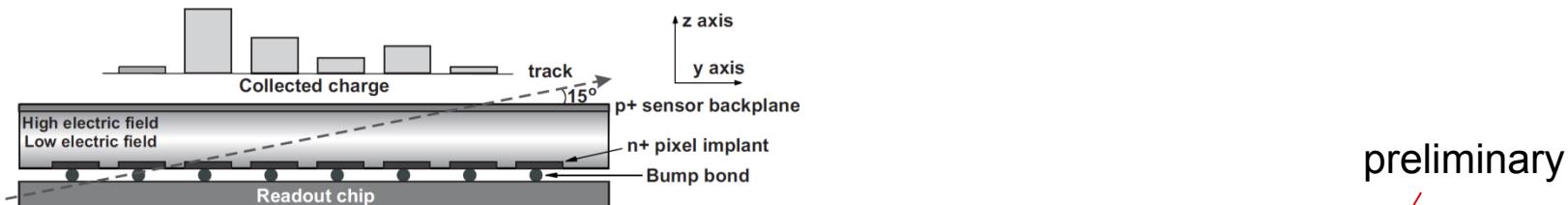


Backup →

Tuning of two effective defects

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For 285 μm thick pixel sensors (125 μm x 125 μm , n-in-n with p-spray isolation)



Tuned: N_D , N_A , σ_e^D , σ_h^D , σ_e^A , σ_h^A

$\Phi [10^{14} \text{ n}_{\text{eq}} \text{ cm}^{-2}]$	0.5	2.0	5.9	12
$N_A [10^{14} \text{ cm}^{-3}]$	1.9	6.8	16	30.
$N_D [10^{14} \text{ cm}^{-3}]$	2.5	10	40	69.
$\sigma_e^{A/D} [10^{-15} \text{ cm}^2]$	6.60	6.60	6.60	3.8/0.94
$\sigma_h^A [10^{-15} \text{ cm}^2]$	1.65	1.65	1.65	3.8
$\sigma_h^D [10^{-15} \text{ cm}^2]$	6.60	6.60	1.65	0.94
$\Gamma_e [10^{-2} \text{ ns}^{-2}]$	2.7	9.6	28.	41.
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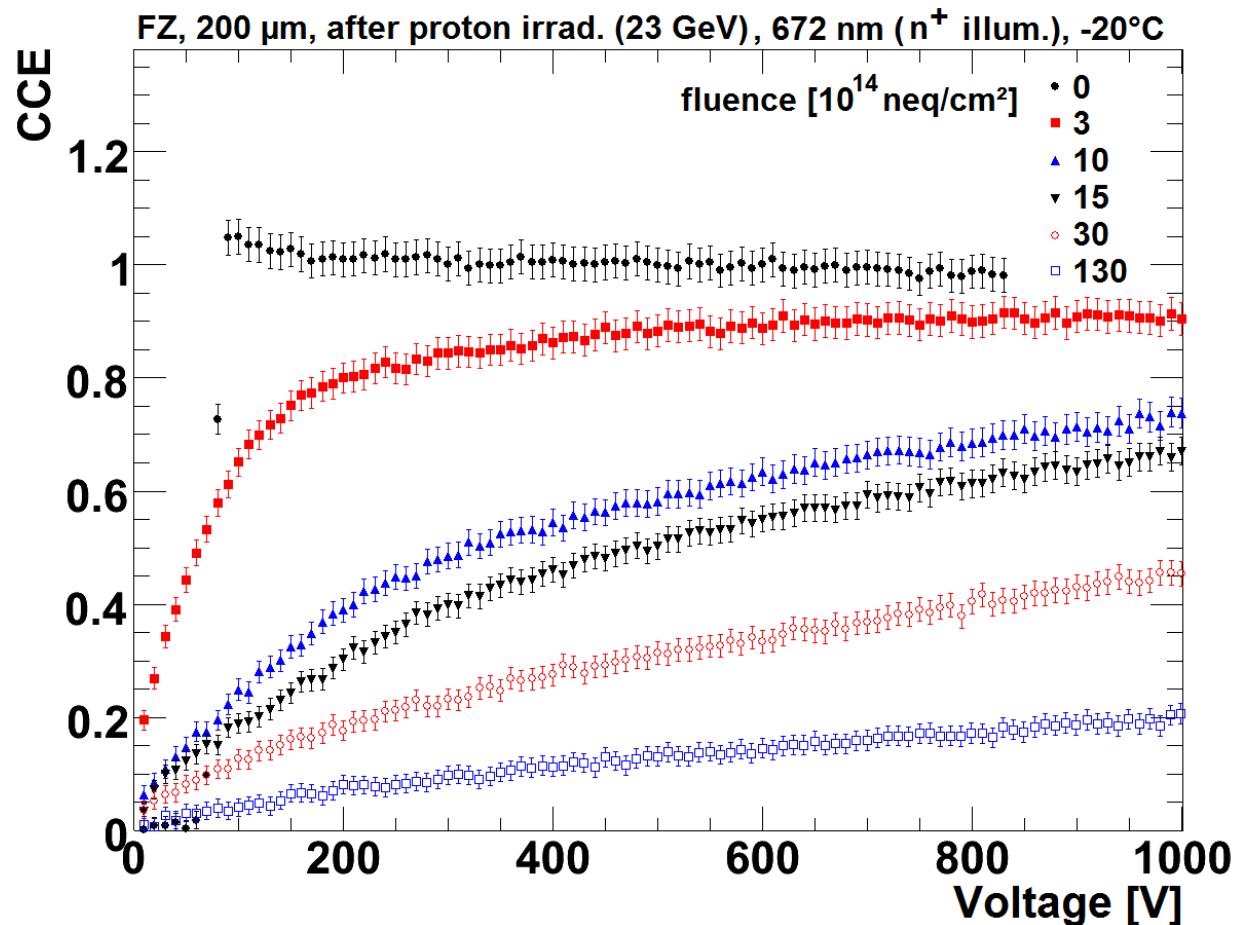
preliminary

defects to describe E-field

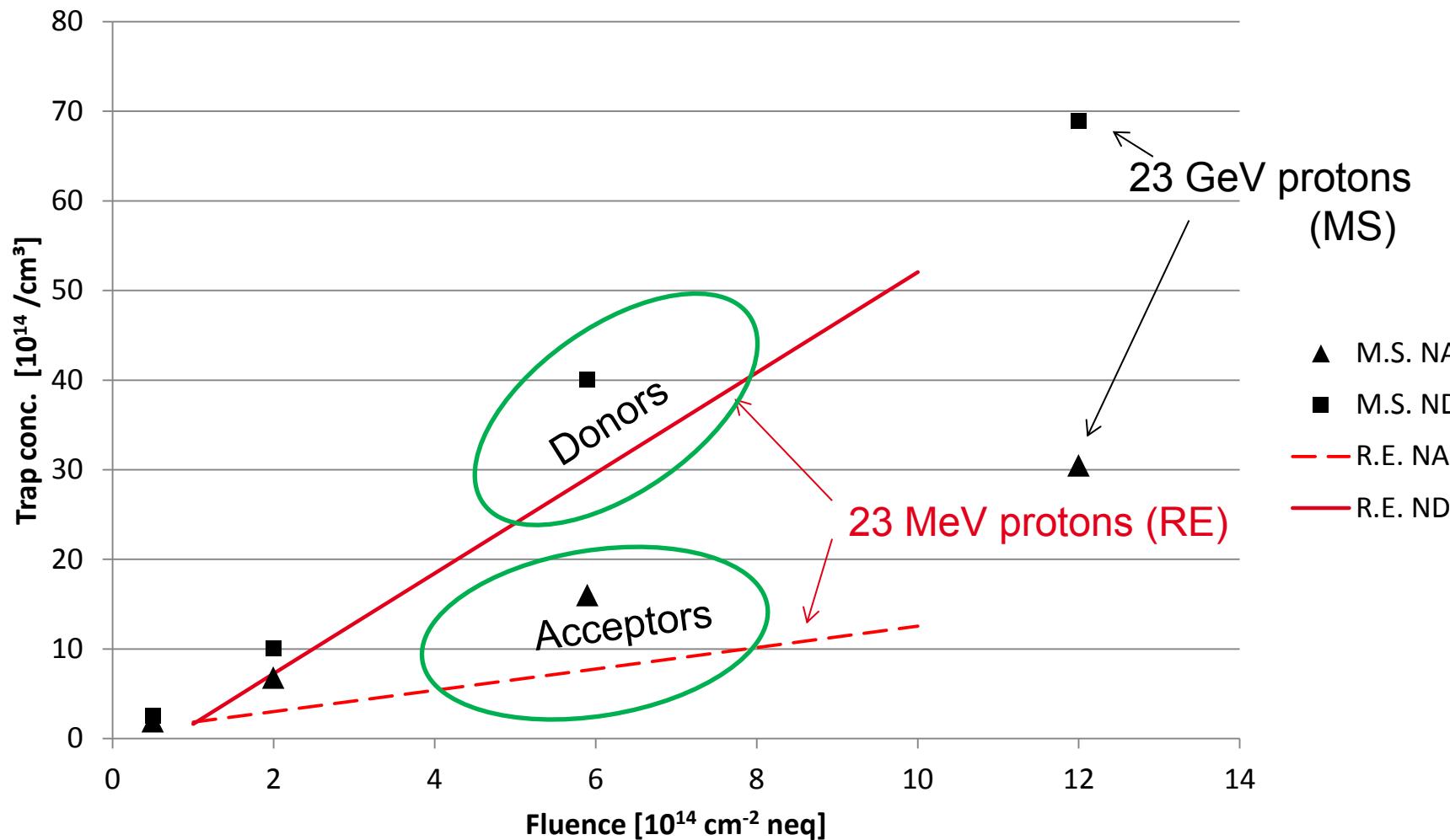
trapping rates used in PixelAV

CCE for holes (illumination at n⁺)

$$CCE = \frac{Q_{irradiated}}{Q_{non-irradiated}^{400V}} = \frac{Q}{Q_0}$$



Defect concentration according to M. Swartz and R. Eber



Bulk damage

Due to non-ionising energy loss (NIEL) **defects** in the Si lattice are generated

⇒ **new states in the energy band gap – responsible for ...**

- ... additional **space charge** -> **operation voltages / thin sensors / oxygen conc.**
- ... **current generation** -> heat and noise -> **more cooling**
- ... **charge trapping** -> signal reduction -> **ROCs with suffic. low threshold**

Defects may be simplified to an **2 effective defects***:

- „Donor“ at $E = E_V + 0.48 \text{ eV}$
- „Acceptor“ at $E = E_C - 0.525 \text{ eV}$

Concentrations and cross sections can be tuned in order to agree with charge collection measurements.

Typically free parameters are:

$$N_D, N_A, \sigma_e^D, \sigma_h^D, \sigma_e^A, \sigma_h^A$$



RD50: Development of radiation tolerant silicon sensors

Defect	$\sigma_{n,p} [\text{cm}^2]$	$E_A [\text{eV}]$	Assignment and impact on sensor
E(30K)	$\sigma_n = 2.3 \times 10^{-14}$	$E_C - 0.1$	Electron trap with donor level in upper half of bandgap; generates positive spacecharge; higher generation in oxygen rich material; higher generation after proton than after neutron irradiation [4].
$BD_A^{(0/++)}$ $BD_B^{(+/++)}$	$\sigma_n = 2.3 \times 10^{-14}$ $\sigma_n = 2.7 \times 10^{-12}$	$E_C - 0.225$ $E_C - 0.15$	Bistable Thermal Double Donor TDD2; electron trap with donor levels in the upper half of bandgap; introducing positive spacecharge; strongly produced in oxygen rich material [5].
$I_p^{(+/0)}$ $I_p^{(0/-)}$	$\sigma_p = (0.5 - 9) \times 10^{-15}$ $\sigma_n = 1.7 \times 10^{-15}$ $\sigma_p = 9 \times 10^{-14}$	$E_V - 0.23$ $E_C - 0.55$	V_2O or carbon related defect with donor and acceptor level; introducing negative spacecharge and leakage current; strongly generated in oxygen lean material [4].
E4 E5	$\sigma_n = 1 \times 10^{-15}$ $\sigma_n = 7.8 \times 10^{-15}$	$E_C - 0.38$ $E_C - 0.46$	Acceptor levels assigned to the double and single charged acceptor states of V_3 ; generating leakage current [6].
$H(116K)$ $H(140K)$ $H(152K)$	$\sigma_p = 4.0 \times 10^{-14}$ $\sigma_p = 2.5 \times 10^{-15}$ $\sigma_p = 2.3 \times 10^{-14}$	$E_V + 0.33$ $E_V + 0.36$ $E_V + 0.42$	Acceptor levels; extended defects (clusters of interstitials or vacancies); introducing negative spacecharge [7].

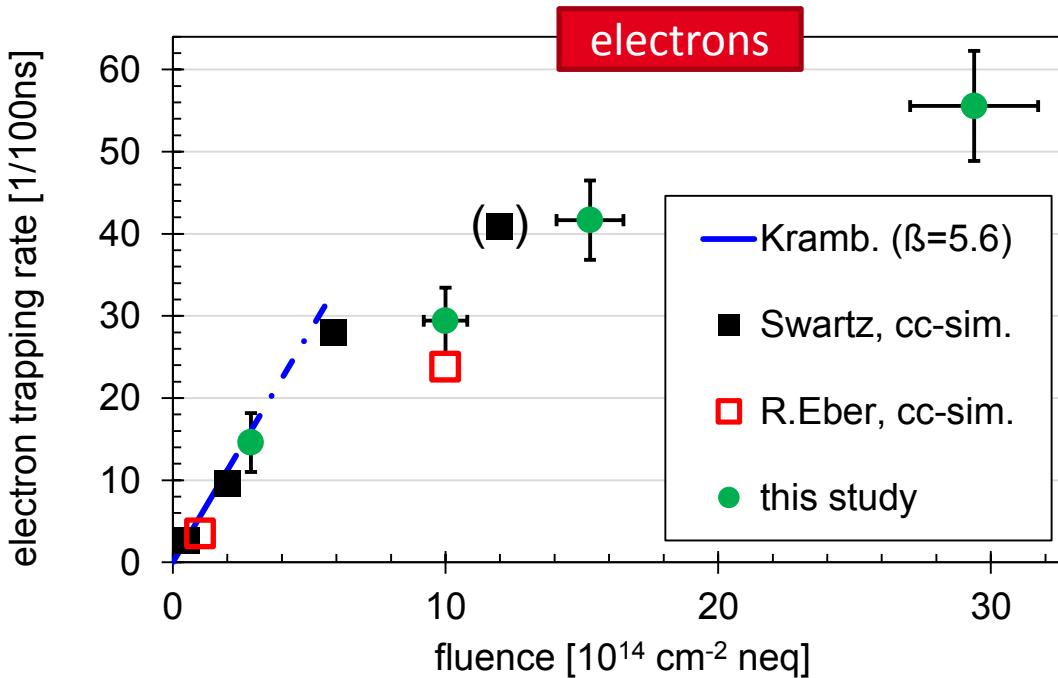
Table 1: List of radiation induced defect levels with a major impact on silicon sensor performance. Given are the defect labels, the cross sections σ_n and σ_p for electrons and holes, the energy level in the band gap E_A with respect to either the conduction (E_C) or the valance (E_V) band and a very brief description of the impact on the sensor.

***EVL model:** NIM A 476 (2002) 556-564.

Results on the trapping rate

After 23 GeV protons:

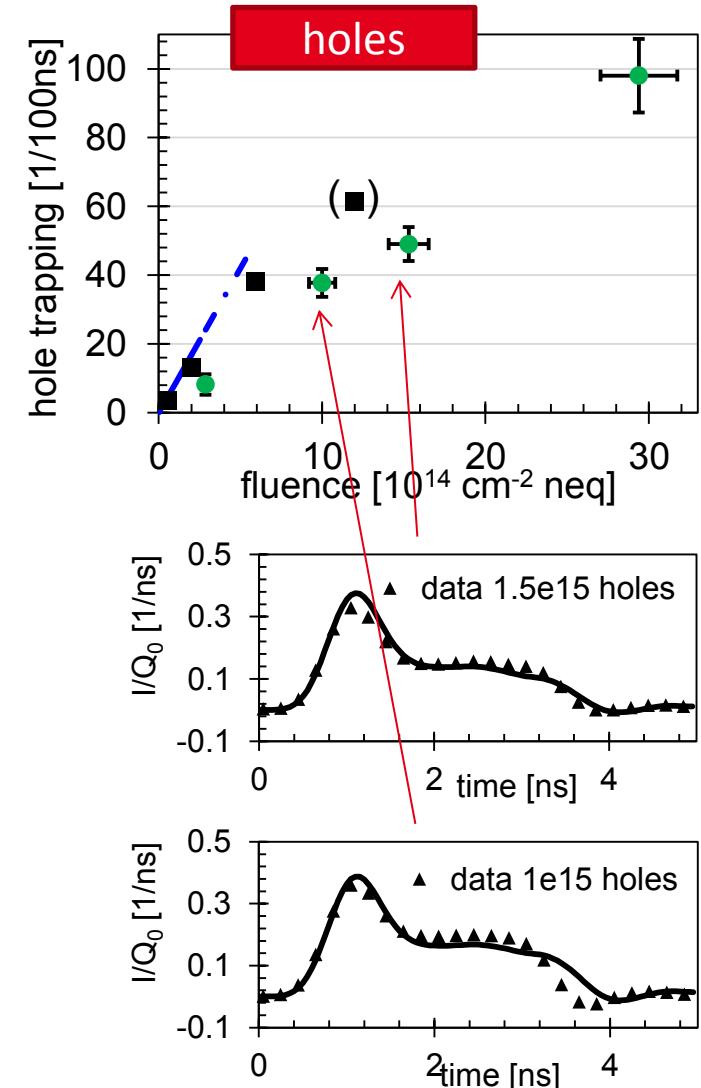
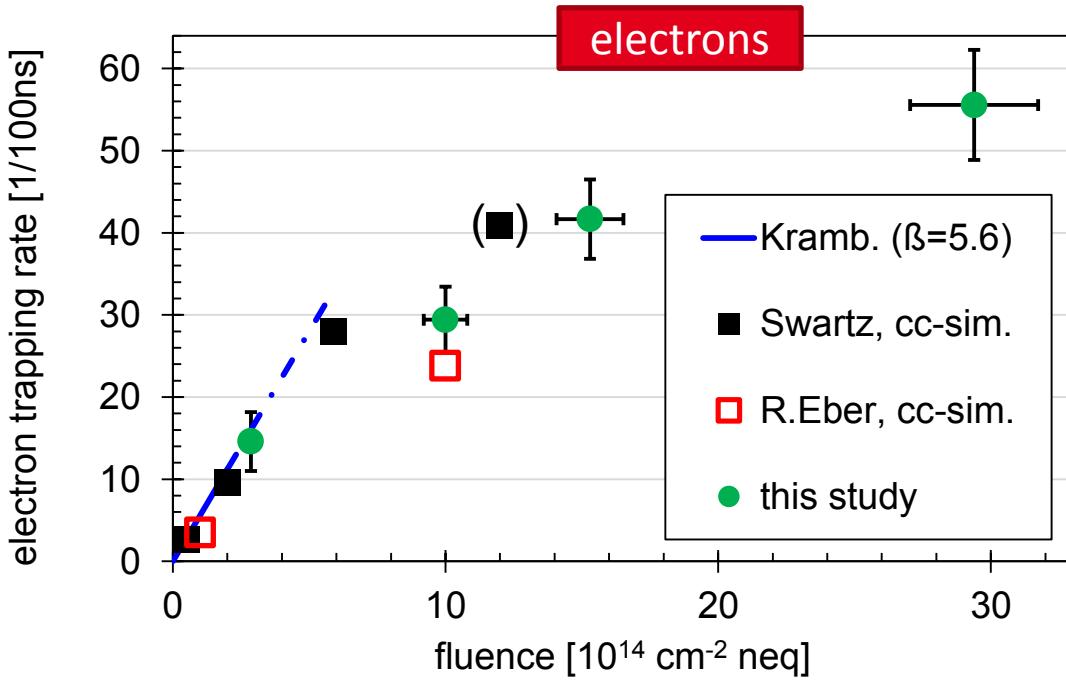
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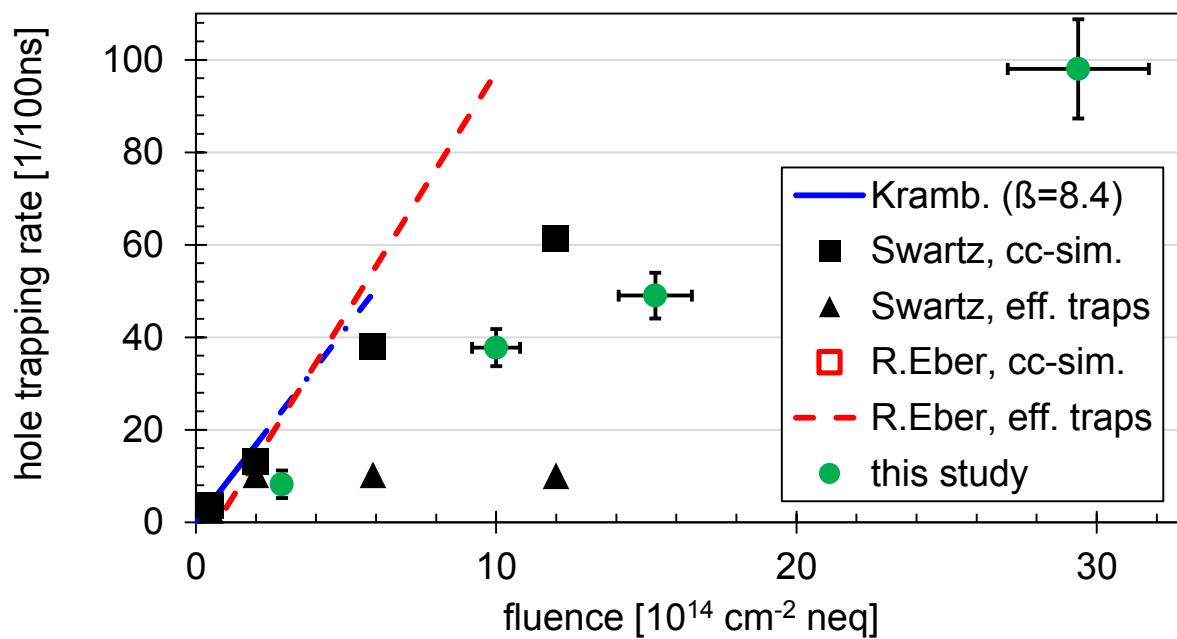


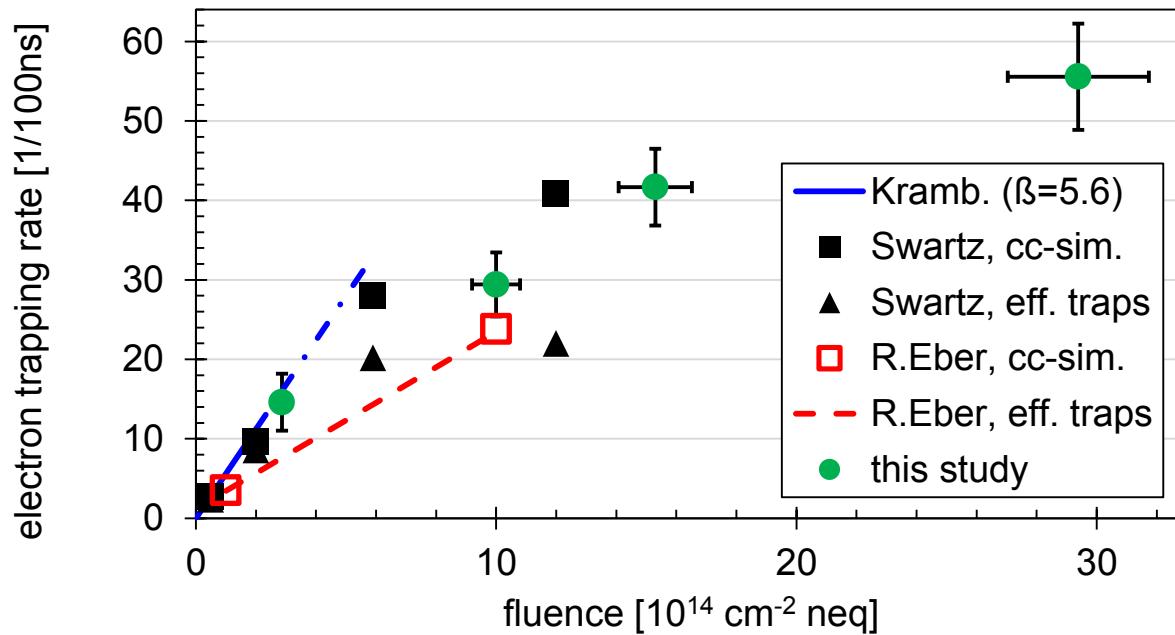
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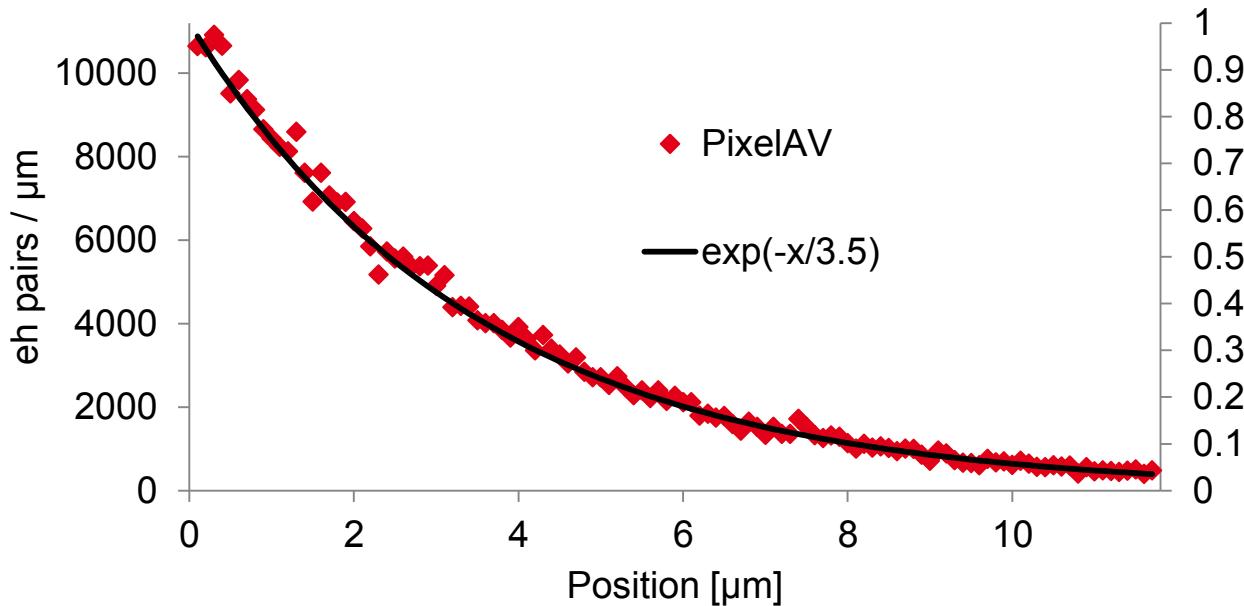


Eh-pair generation by laser light in PixelAV

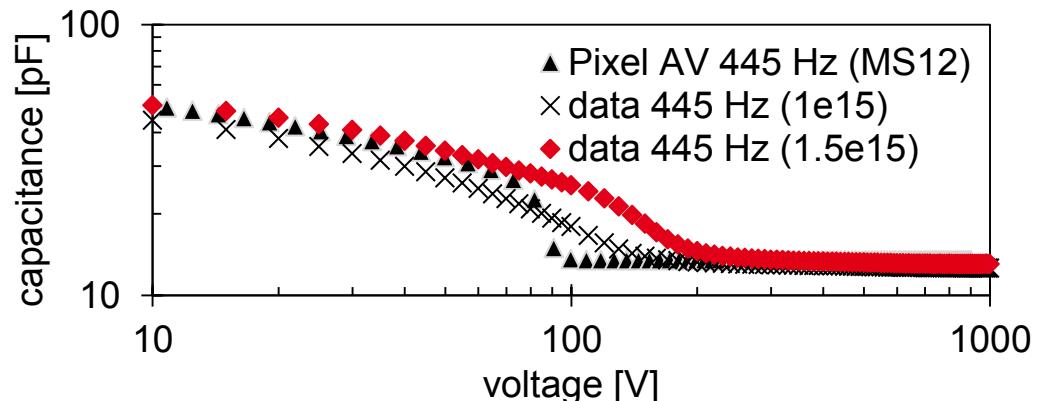
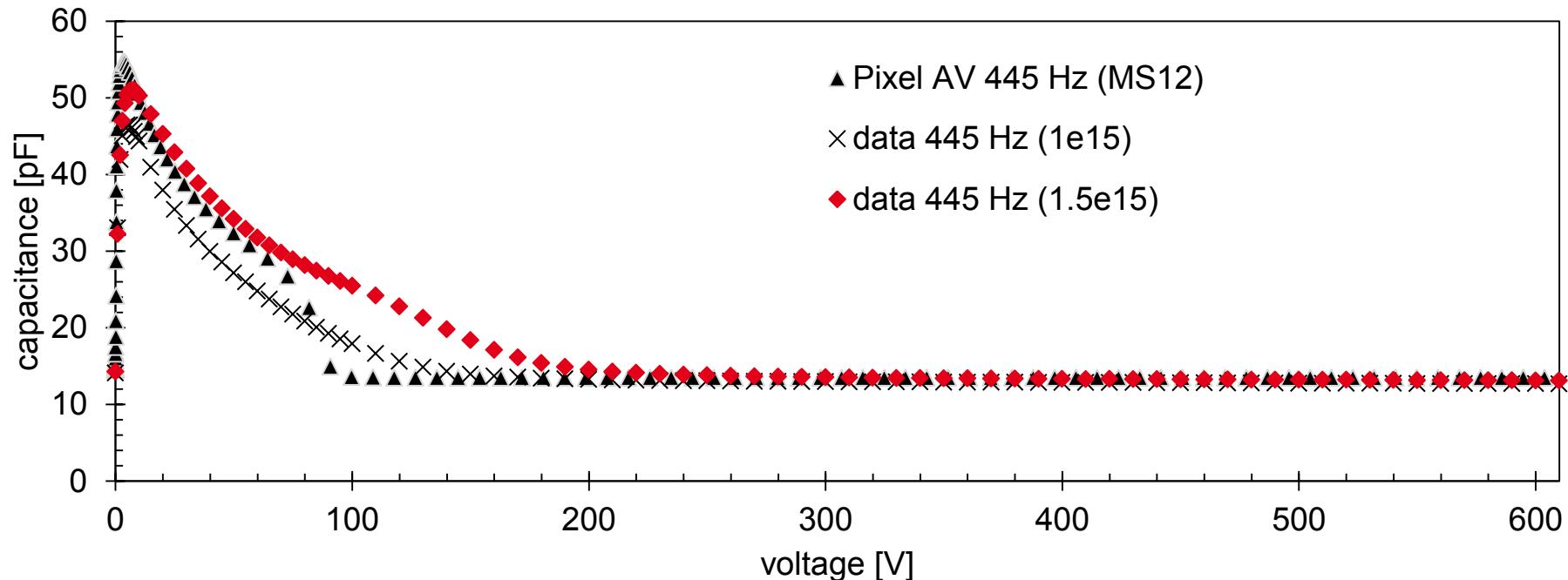
Each eh pair is generated with a random generator.

The generated eh pairs are distributed according to a penetration depth of 3.5 μm

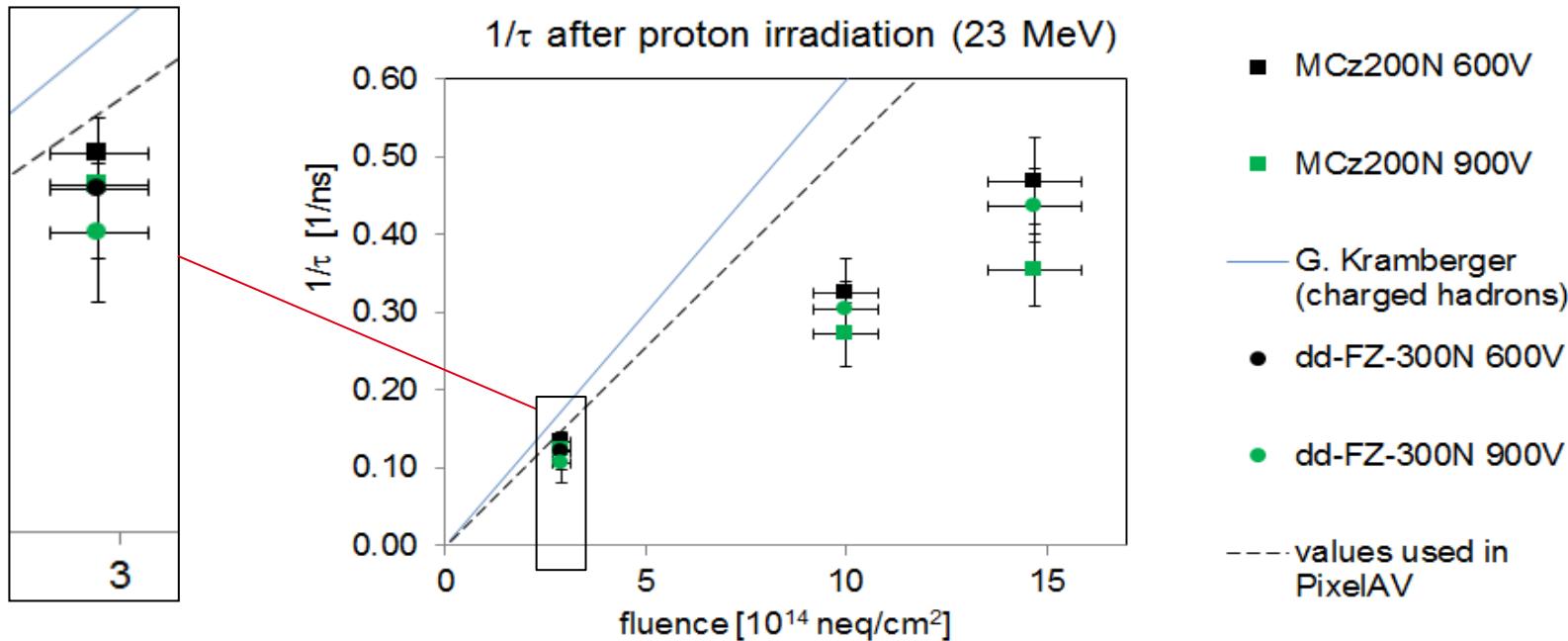
40 000 eh pairs are generated at the front:



CV curves: 2 x data and 1 x simulation



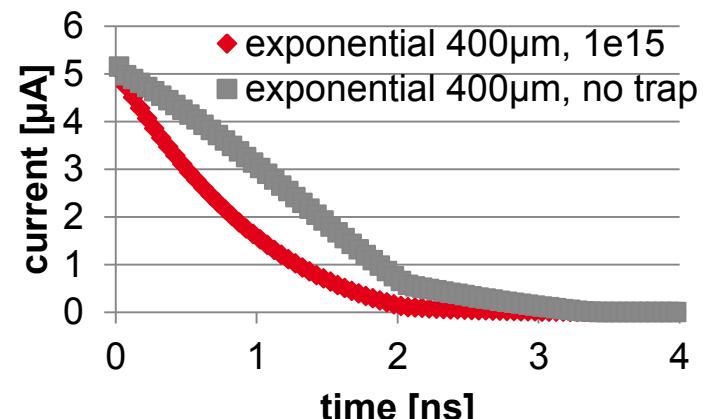
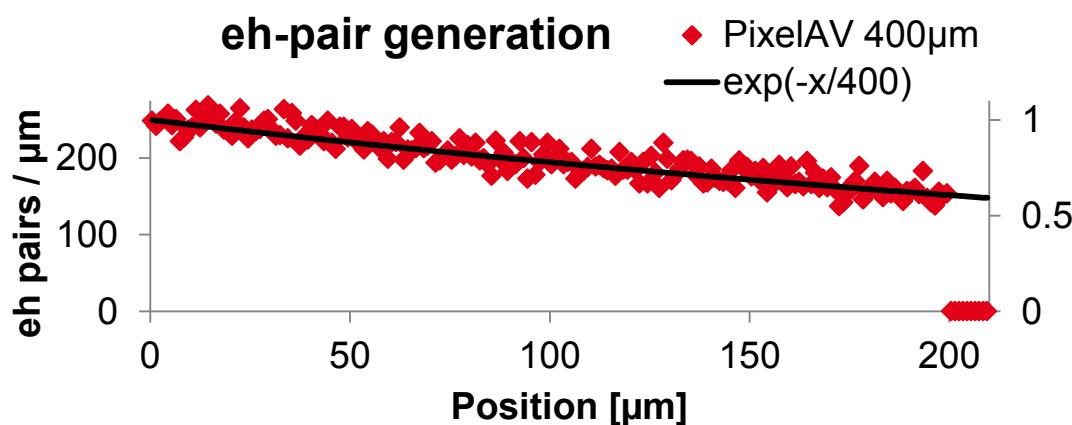
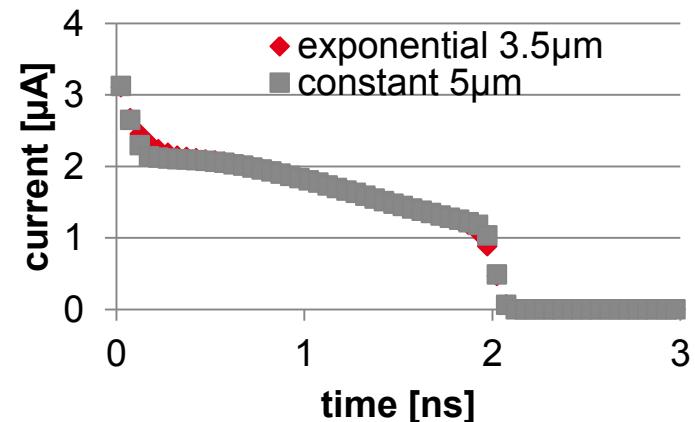
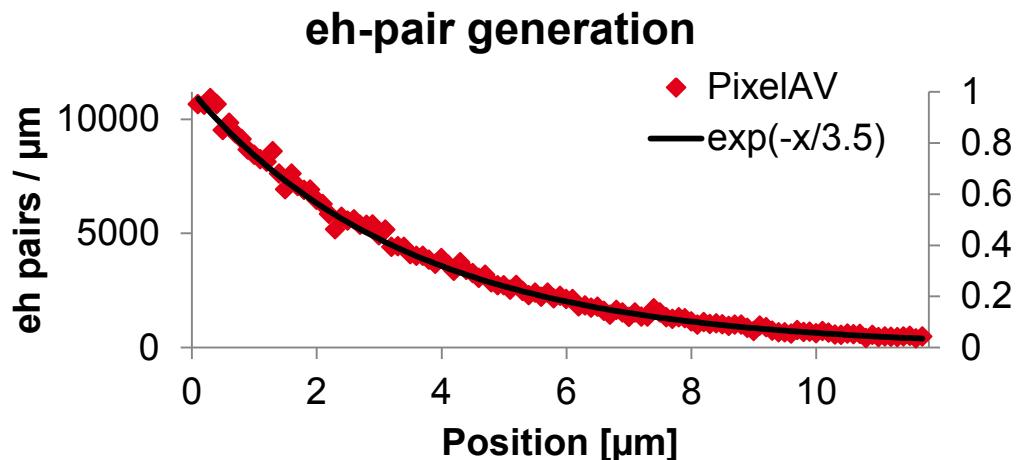
Electron trapping rates in 200 and 300 μm thick sensors



For this plot E=const was assumed

Trapping times for electrons at high fluences are lower compared to expectations by G. Kramberger also for MCz and dd-FZ 300 μm thick materials.

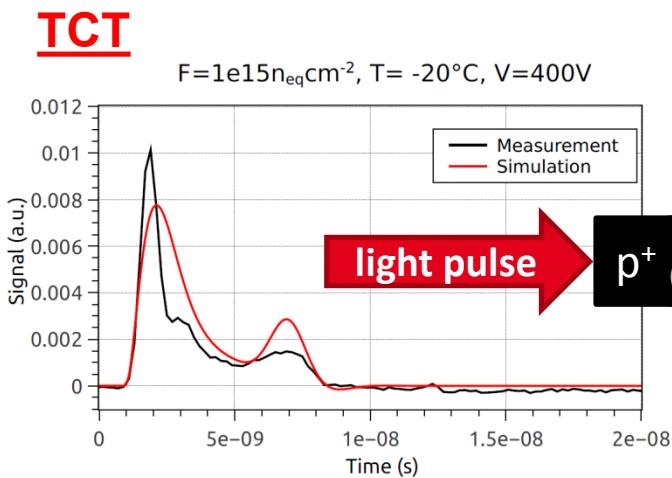
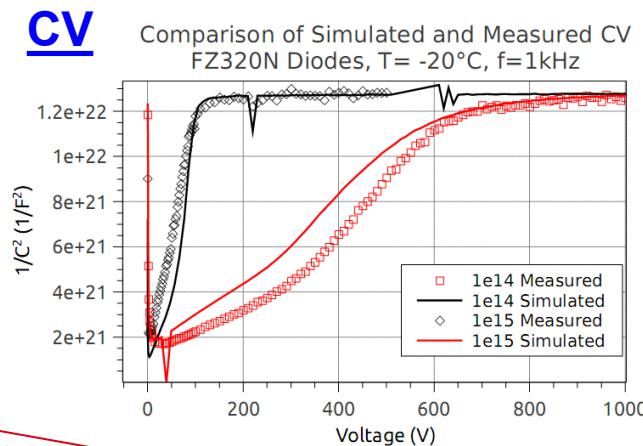
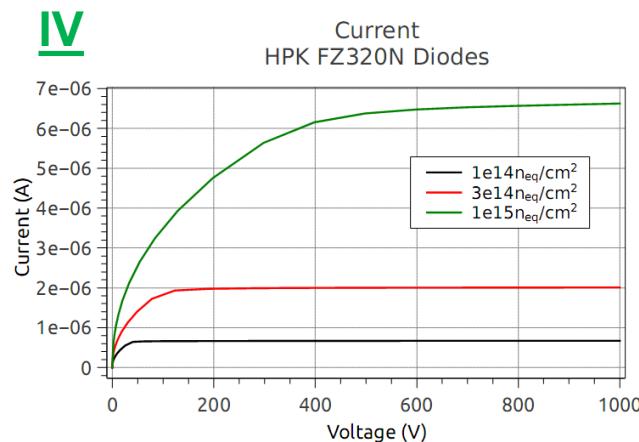
Charge deposition with light



Eh-pair generation implemented for different
Absorption lengths ✓

Tuning of the effective 2-defect model

Fit in TCAD by Robert Eber (KIT) using **current**, **capacitance** and **red laser TCT** meas.
after **23 MeV proton irradiation**, 300 μm thick, dd-FZ p-on-n pad sensors



$N_D, N_A, \sigma_e^D, \sigma_h^D, \sigma_e^A, \sigma_h^A$

Parameters tuned:

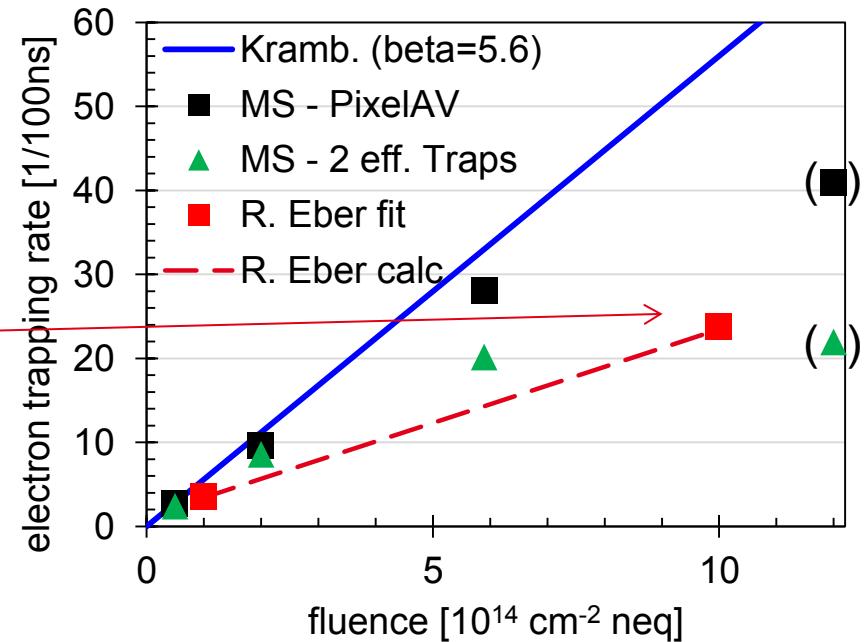
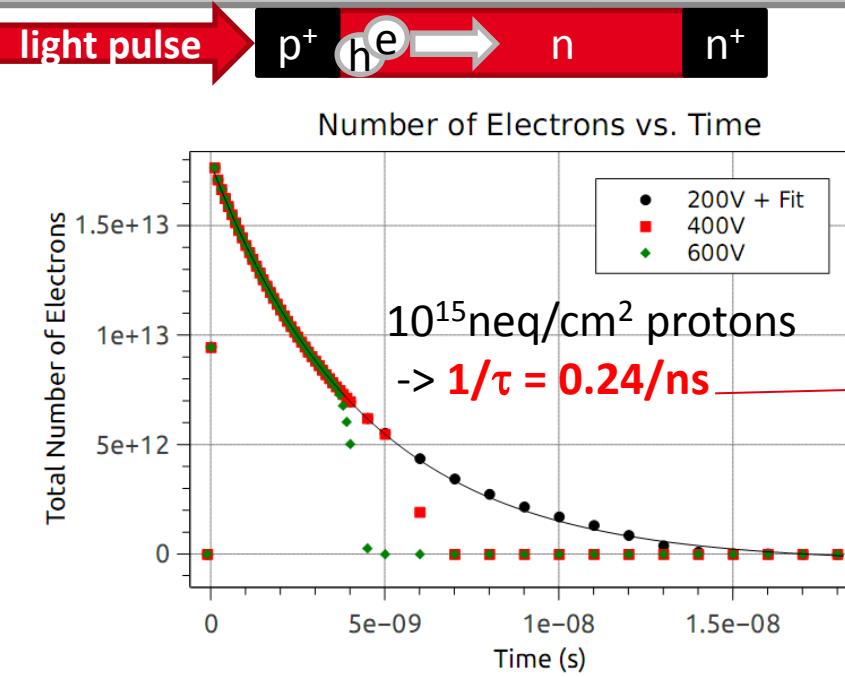
- Donor
 - N_D ■ $c = 5.598 * F - 3.959e14$
 - $\sigma_{e,h}^D$ ■ $X(e) = X(h) = 1.0e-14\text{cm}^2$
- Acceptor
 - N_A ■ $c = 1.189 * F + 0.645e14$
 - $\sigma_{e,h}^A$ ■ $X(e) = X(h) = 1.0e-14\text{cm}^2$

50% initial donor removal

see **Robert Eber's thesis**:
 KIT – EKP-2014-0012
 (ekp.kit.edu/391.php)

Tuning of the effective 2-defect model

... and consequences for trapping



Defect parameters were extracted with two different approaches:

- R. Eber: capacitance, current and red laser TCT measurements in TCAD
- M. Swartz: grazing-angle test beam measurements in PixelAV supported by TCAD

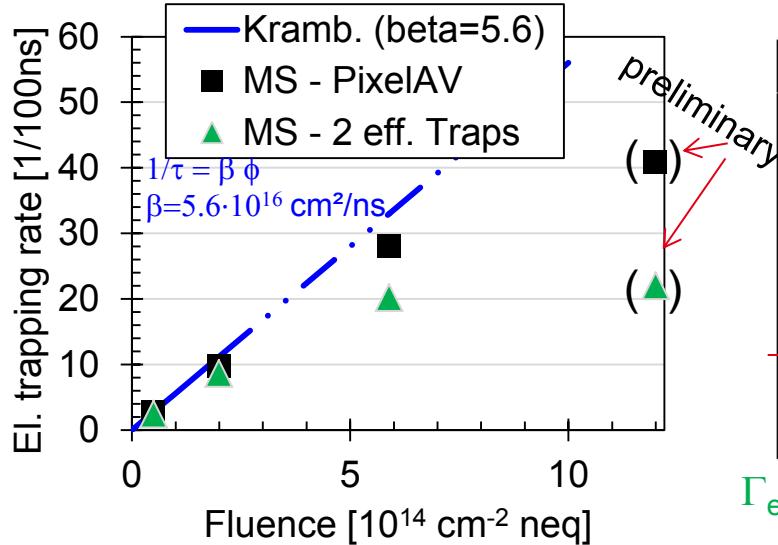
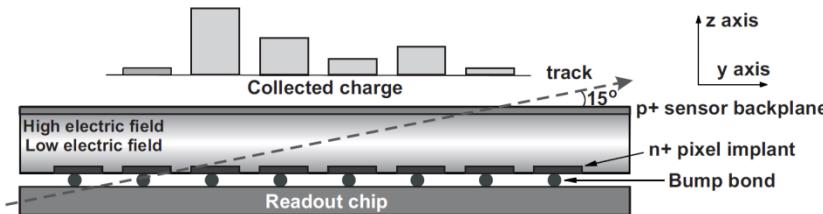
⇒ Trapping rates lower than expected at high fluences !

Can we determine the effective trapping rate directly from measured charge losses?

Tuning of two effective defects

Fit by Morris Swartz et al. using TCAD and self-written „PixelAV“ simulation program to describe grazing angle measurements ([arXiv:physics/0605215](https://arxiv.org/abs/physics/0605215)):

For 285 μm thick pixel sensors (125 μm x 125 μm , n-in-n with p-spray isolation)



$\Phi [10^{14} \text{ n}_{\text{eq}} \text{ cm}^{-2}]$	0.5	2.0	5.9	12
$N_A [10^{14} \text{ cm}^{-3}]$	1.9	6.8	16	30.
$N_D [10^{14} \text{ cm}^{-3}]$	2.5	10	40	69.
$\sigma_e^{A/D} [10^{-15} \text{ cm}^2]$	6.60	6.60	6.60	3.8/0.94
$\sigma_h^A [10^{-15} \text{ cm}^2]$	1.65	1.65	1.65	3.8
$\sigma_h^D [10^{-15} \text{ cm}^2]$	6.60	6.60	1.65	0.94
$\Gamma_e [10^{-2} \text{ ns}^{-2}]$	2.7	9.6	28.	41
$\Gamma_h [10^{-2} \text{ ns}^{-2}]$	3.6	13.	38.	55.

$\Gamma_e, \text{calculated from traps: } [2.4 \quad 8.6 \quad 20. \quad 22.]$
 $(\Gamma_e = 1.91e7 \text{ cm/s} \cdot \sigma_e^A \cdot N_A)$

preliminary

defects to describe E-field

trapping rates used in PixelAV

trapping rates in TCAD (E-field)